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Understanding Embedded - CPLDs (Complex Programmable Logic Devices)

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixed-function ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

Applications of Embedded - CPLDs

Details

Product Status	Obsolete
Programmable Type	In System Programmable
Delay Time tpd(1) Max	5.5 ns
Voltage Supply - Internal	4.75V ~ 5.25V
Number of Logic Elements/Blocks	-
Number of Macrocells	64
Number of Gates	-
Number of I/O	32
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	44-TQFP
Supplier Device Package	44-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/m4a5-64-32-55vc

Table 1. ispMACH 4A Device Features

3.3 V Devices								
Feature	M4A3-32	M4A3-64	M4A3-96	M4A3-128	M4A3-192	M4A3-256	M4A3-384	M4A3-512
Macrocells	32	64	96	128	192	256	384	512
User I/O options	32	32/64	48	64	96	128/160/192	160/192	160/192/256
t _{PD} (ns)	5.0	5.5	5.5	5.5	6.0	5.5	6.5	7.5
f _{CNT} (MHz)	182	167	167	167	160	167	154	125
t _{COS} (ns)	4.0	4.0	4.0	4.0	4.5	4.0	4.5	5.5
t _{SS} (ns)	3.0	3.5	3.5	3.5	3.5	3.5	3.5	5.0
Static Power (mA)	20	25/52	40	55	85	110/150	149/155	179
JTAG Compliant	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes
PCI Compliant	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes

5 V Devices						
Feature	M4A5-32	M4A5-64	M4A5-96	M4A5-128	M4A5-192	M4A5-256
Macrocells	32	64	96	128	192	256
User I/O options	32	32	48	64	96	128
t _{PD} (ns)	5.0	5.5	5.5	5.5	6.0	6.5
f _{CNT} (MHz)	182	167	167	167	160	154
t _{COS} (ns)	4.0	4.0	4.0	4.0	4.5	5.0
t _{SS} (ns)	3.0	3.5	3.5	3.5	3.5	3.5
Static Power (mA)	20	25	40	55	74	110
JTAG Compliant	Yes	Yes	Yes	Yes	Yes	Yes
PCI Compliant	Yes	Yes	Yes	Yes	Yes	Yes

GENERAL DESCRIPTION

The ispMACH™ 4A family from Lattice offers an exceptionally flexible architecture and delivers a superior Complex Programmable Logic Device (CPLD) solution of easy-to-use silicon products and software tools. The overall benefits for users are a guaranteed and predictable CPLD solution, faster time-to-market, greater flexibility and lower cost. The ispMACH 4A devices offer densities ranging from 32 to 512 macrocells with 100% utilization and 100% pin-out retention. The ispMACH 4A families offer 5-V (M4A5-xxx) and 3.3-V (M4A3-xxx) operation.

ispMACH 4A products are 5-V or 3.3-V in-system programmable through the JTAG (IEEE Std. 1149.1) interface. JTAG boundary scan testing also allows product testability on automated test equipment for device connectivity.

All ispMACH 4A family members deliver First-Time-Fit and easy system integration with pin-out retention after any design change and refit. For both 3.3-V and 5-V operation, ispMACH 4A products can deliver guaranteed fixed timing as fast as 5.0 ns t_{PD} and 182 MHz f_{CNT} through the SpeedLocking feature when using up to 20 product terms per output (Table 2).

Table 2. ispMACH 4A Speed Grades

Device	Speed Grade							
	-5	-55	-6	-65	-7	-10	-12	-14
M4A3-32	C				C, I	C, I	I	
M4A5-32								
M4A3-64/32		C			C, I	C, I	I	
M4A5-64/32								
M4A3-64/64		C			C, I	C, I	I	
M4A3-96		C			C, I	C, I	I	
M4A5-96								
M4A3-128		C			C, I	C, I	I	
M4A5-128								
M4A3-192			C		C, I	C, I	I	
M4A5-192								
M4A3-256/128		C		C	C, I	C, I	I	
M4A5-256/128				C	C	C, I	I	
M4A3-256/192					C	C, I	I	
M4A3-256/160								
M4A3-384				C		C, I	C, I	I
M4A3-512					C	C, I	C, I	I

Note:

1. C = Commercial I = Industrial

The ispMACH 4A family offers 20 density-I/O combinations in Thin Quad Flat Pack (TQFP), Plastic Quad Flat Pack (PQFP), Plastic Leaded Chip Carrier (PLCC), Ball Grid Array (BGA), fine-pitch BGA (fpBGA), and chip-array BGA (caBGA) packages ranging from 44 to 388 pins (Table 3). It also offers I/O safety features for mixed-voltage designs so that the 3.3-V devices can accept 5-V inputs, and 5-V devices do not overdrive 3.3-V inputs. Additional features include Bus-Friendly inputs and I/Os, a programmable power-down mode for extra power savings and individual output slew rate control for the highest speed transition or for the lowest noise transition.

Table 3. ispMACH 4A Package and I/O Options (Number of I/Os and dedicated inputs in Table)

3.3 V Devices								
Package	M4A3-32	M4A3-64	M4A3-96	M4A3-128	M4A3-192	M4A3-256	M4A3-384	M4A3-512
44-pin PLCC	32+2	32+2						
44-pin TQFP	32+2	32+2						
48-pin TQFP	32+2	32+2						
100-pin TQFP		64+6	48+8	64+6				
100-pin PQFP				64+6				
100-ball caBGA				64+6				
144-pin TQFP					96+16			
144-ball fpBGA					96+16			
208-pin PQFP						128+14, 160	160	160
256-ball fpBGA						128+14, 192	192	192
256-ball BGA						128+14	192	
388-ball fpBGA								256

5 V Devices						
Package	M4A5-32	M4A5-64	M4A5-96	M4A5-128	M4A5-192	M4A5-256
44-pin PLCC	32+2	32+2				
44-pin TQFP	32+2	32+2				
48-pin TQFP	32+2	32+2				
100-pin TQFP			48+8	64+6		
100-pin PQFP				64+6		
144-pin TQFP					96+16	
208-pin PQFP						128+14

Macrocell

The macrocell consists of a storage element, routing resources, a clock multiplexer, and initialization control. The macrocell has two fundamental modes: synchronous and asynchronous (Figure 5). The mode chosen only affects clocking and initialization in the macrocell.

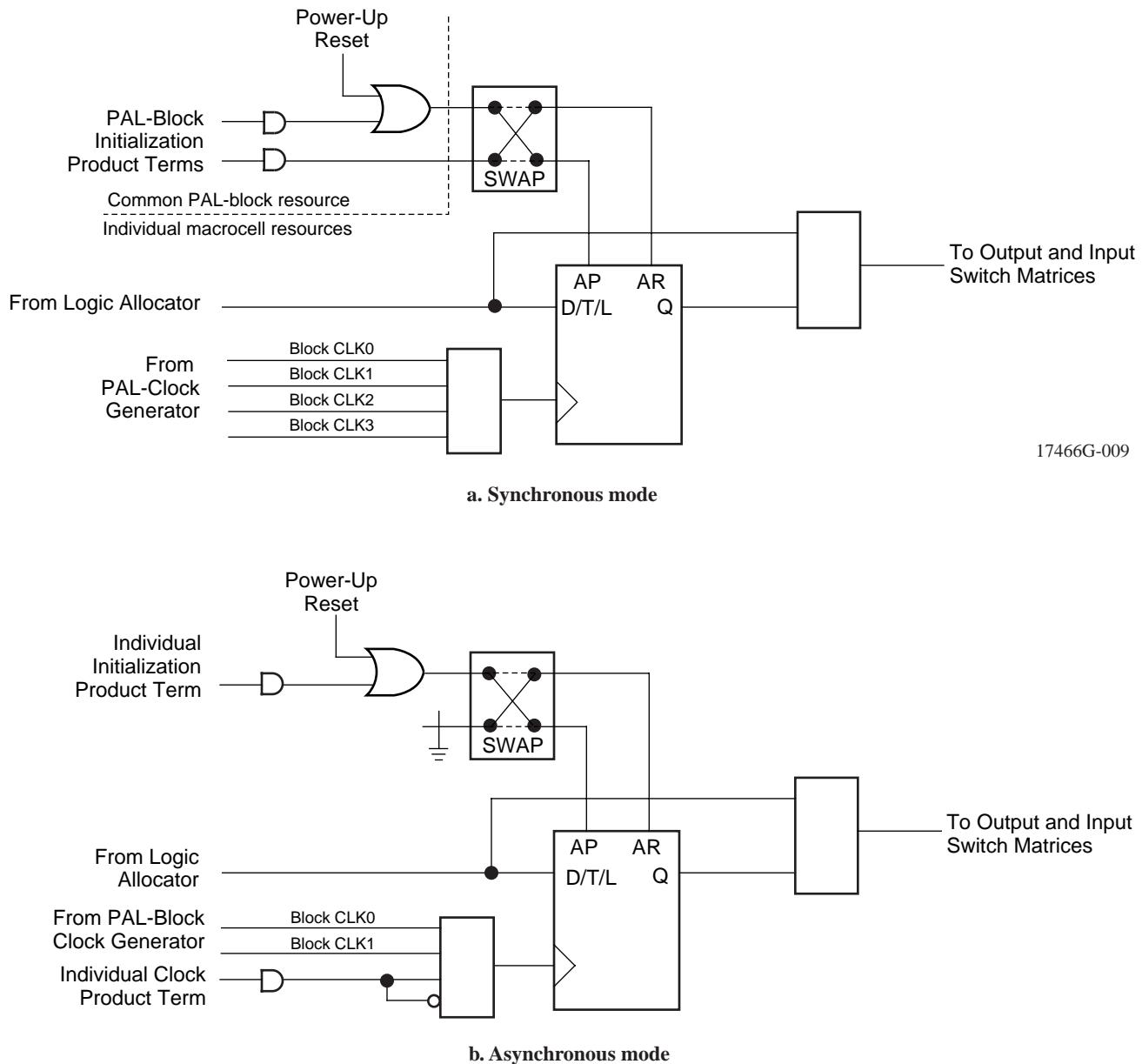


Figure 5. Macrocell

In either mode, a combinatorial path can be used. For combinatorial logic, the synchronous mode will generally be used, since it provides more product terms in the allocator.

Table 8. Register/Latch Operation

Configuration	Input(s)	CLK/LE ¹	Q+
D-type Register	D=X	0, 1, ↓ (↑)	Q
	D=0	↑ (↓)	0
	D=1	↑ (↓)	1
T-type Register	T=X	0, 1, ↓ (↑)	Q
	T=0	↑ (↓)	Q
	T=1	↑ (↓)	Q̄
D-type Latch	D=X	1(0)	Q
	D=0	0(1)	0
	D=1	0(1)	1

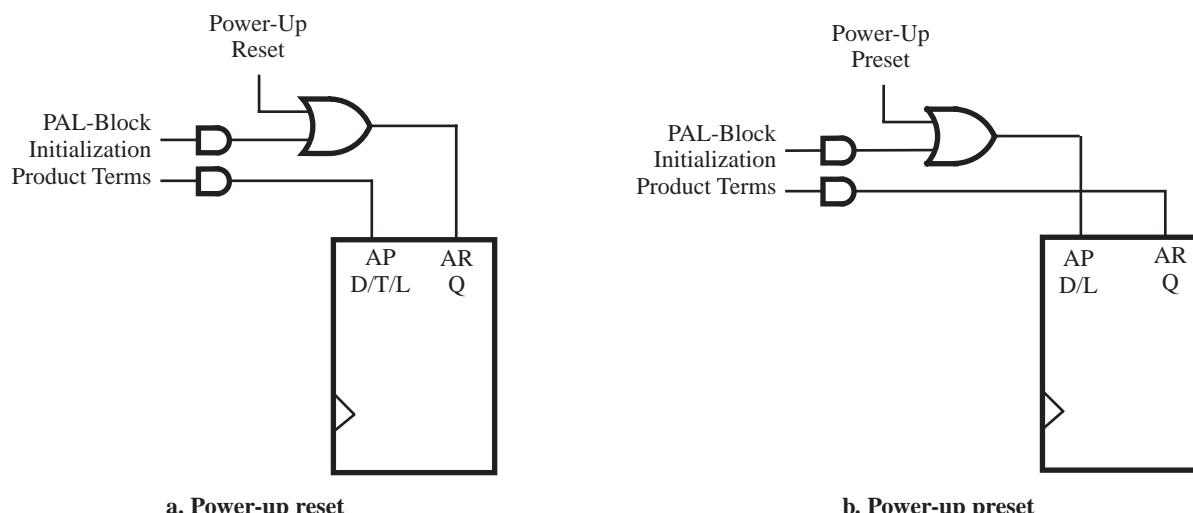
Note:

1. Polarity of CLK/LE can be programmed

Although the macrocell shows only one input to the register, the XOR gate in the logic allocator allows the D-, T-type register to emulate J-K, and S-R behavior. In this case, the available product terms are divided between J and K (or S and R). When configured as J-K, S-R, or T-type, the extra product term must be used on the XOR gate input for flip-flop emulation. In any register type, the polarity of the inputs can be programmed.

The clock input to the flip-flop can select any of the four PAL block clocks in synchronous mode, with the additional choice of either polarity of an individual product term clock in the asynchronous mode.

The initialization circuit depends on the mode. In synchronous mode (Figure 7), asynchronous reset and preset are provided, each driven by a product term common to the entire PAL block.



17466G-012

17466G-013

Figure 7. Synchronous Mode Initialization Configurations

Output Switch Matrix

The output switch matrix allows macrocells to be connected to any of several I/O cells within a PAL block. This provides high flexibility in determining pinout and allows design changes to occur without effecting pinout.

In ispMACH 4A devices with 2:1 Macrocell-I/O cell ratio, each PAL block has twice as many macrocells as I/O cells. The ispMACH 4A output switch matrix allows for half of the macrocells to drive I/O cells within a PAL block, in combinations according to Figure 9. Each I/O cell can choose from eight macrocells; each macrocell has a choice of four I/O cells. The ispMACH 4A devices with 1:1 Macrocell-I/O cell ratio allow each macrocell to drive one of eight I/O cells (Figure 9).

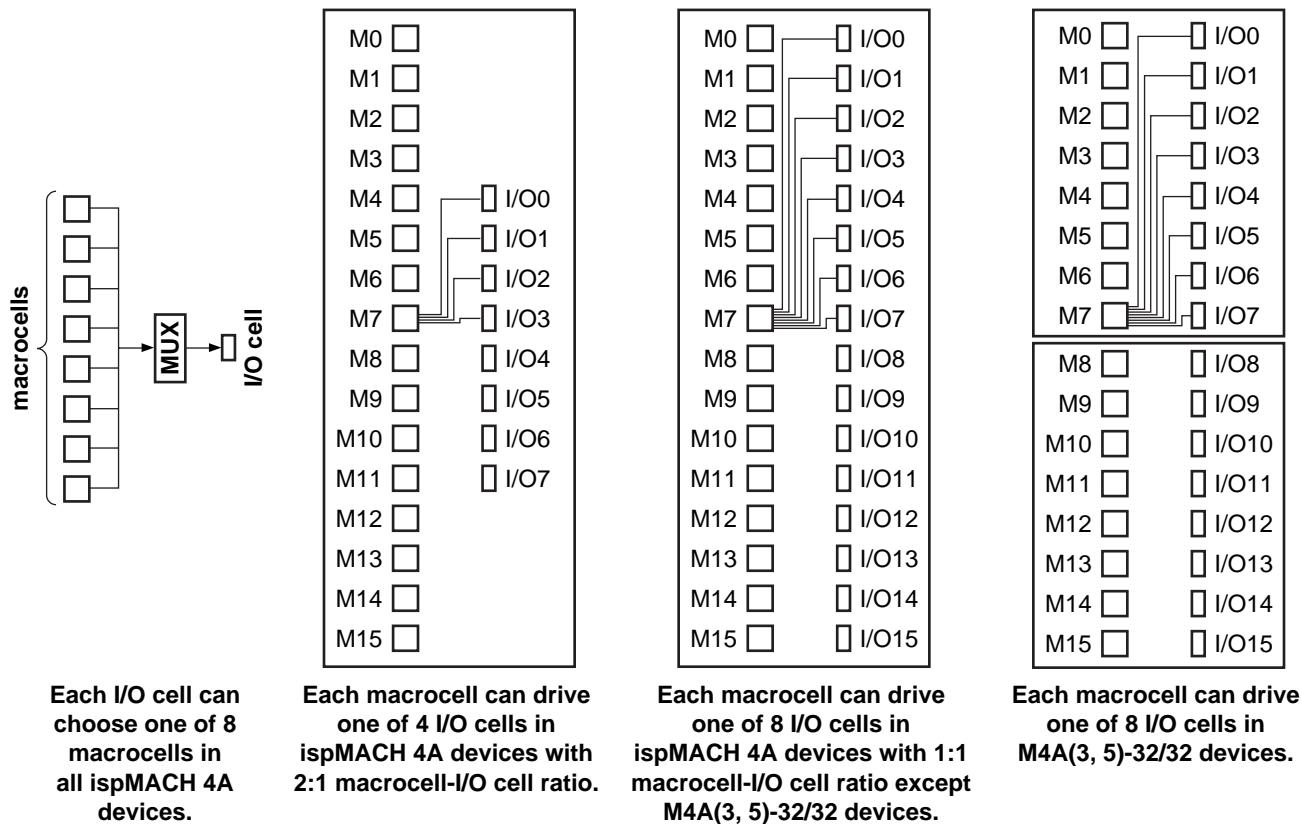


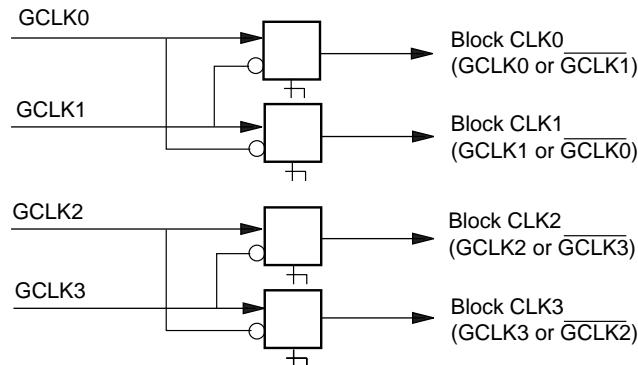
Figure 9. ispMACH 4A Output Switch Matrix

Table 10. Output Switch Matrix Combinations for ispMACH 4A Devices with 2:1 Macrocell-I/O Cell Ratio

Macrocell	Routable to I/O Cells
M0, M1	I/00, I/05, I/06, I/07
M2, M3	I/00, I/01, I/06, I/07
M4, M5	I/00, I/01, I/02, I/07
M6, M7	I/00, I/01, I/02, I/03
M8, M9	I/01, I/02, I/03, I/04
M10, M11	I/02, I/03, I/04, I/05

PAL Block Clock Generation

Each ispMACH 4A device has four clock pins that can also be used as inputs. These pins drive a clock generator in each PAL block (Figure 14). The clock generator provides four clock signals that can be used anywhere in the PAL block. These four PAL block clock signals can consist of a large number of combinations of the true and complement edges of the global clock signals. Table 14 lists the possible combinations.



17466G-004

Figure 14. PAL Block Clock Generator¹

1. M4A(3,5)-32/32 and M4A(3,5)-64/32 have only two clock pins, GCLK0 and GCLK1. GCLK2 is tied to GCLK0, and GCLK3 is tied to GCLK1.

Table 14. PAL Block Clock Combinations¹

Block CLK0	Block CLK1	Block CLK2	Block CLK3
GCLK0	GCLK1	X	X
<u>GCLK1</u>	GCLK1	X	X
GCLK0	<u>GCLK0</u>	X	X
<u>GCLK1</u>	<u>GCLK0</u>	X	X
X	X	GCLK2 (GCLK0)	GCLK3 (GCLK1)
X	X	<u>GCLK3 (GCLK1)</u>	GCLK3 (GCLK1)
X	X	GCLK2 (GCLK0)	<u>GCLK2 (GCLK0)</u>
X	X	<u>GCLK3 (GCLK1)</u>	GCLK2 (GCLK0)

Note:

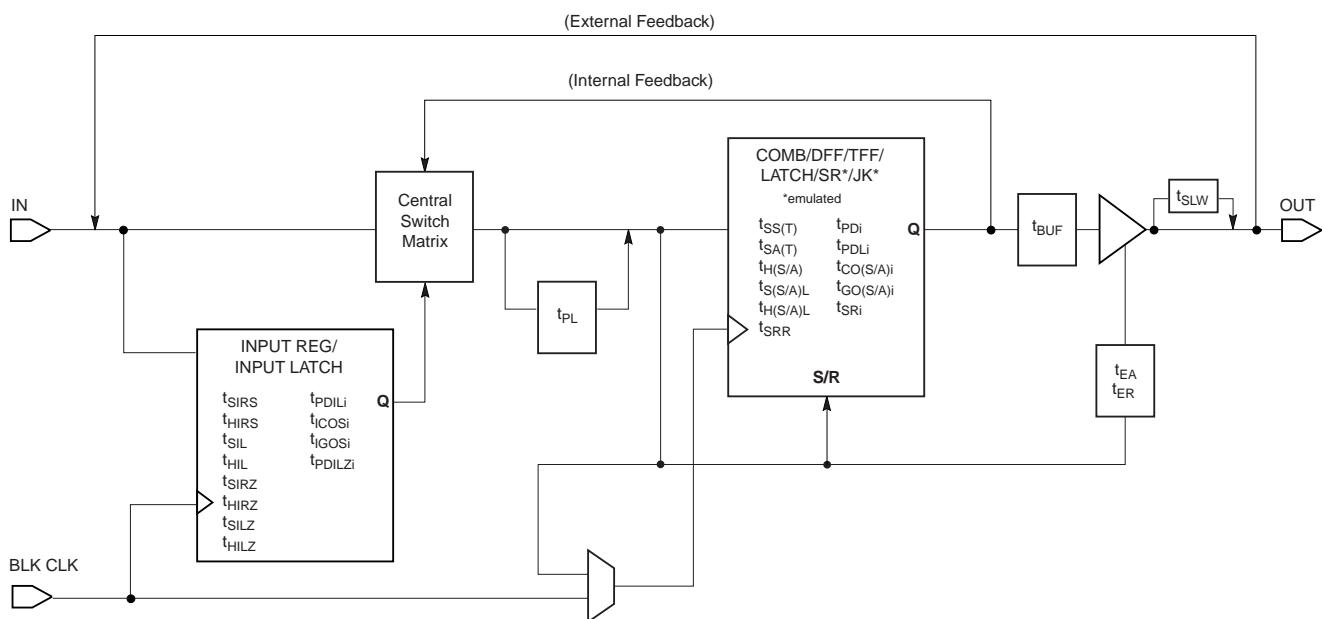
1. Values in parentheses are for the M4A(3,5)-32/32 and M4A(3,5)-64/32.

This feature provides high flexibility for partitioning state machines and dual-phase clocks. It also allows latches to be driven with either polarity of latch enable, and in a master-slave configuration.

ispMACH 4A TIMING MODEL

The primary focus of the ispMACH 4A timing model is to accurately represent the timing in a ispMACH 4A device, and at the same time, be easy to understand. This model accurately describes all combinatorial and registered paths through the device, making a distinction between internal feedback and external feedback. A signal uses internal feedback when it is fed back into the switch matrix or block without having to go through the output buffer. The input register specifications are also reported as internal feedback. When a signal is fed back into the switch matrix after having gone through the output buffer, it is using external feedback.

The parameter, t_{BUF} , is defined as the time it takes to go from feedback through the output buffer to the I/O pad. If a signal goes to the internal feedback rather than to the I/O pad, the parameter designator is followed by an “i”. By adding t_{BUF} to this internal parameter, the external parameter is derived. For example, $t_{PD} = t_{PDI} + t_{BUF}$. A diagram representing the modularized ispMACH 4A timing model is shown in Figure 15. Refer to the application note entitled *MACH 4 Timing and High Speed Design* for a more detailed discussion about the timing parameters.



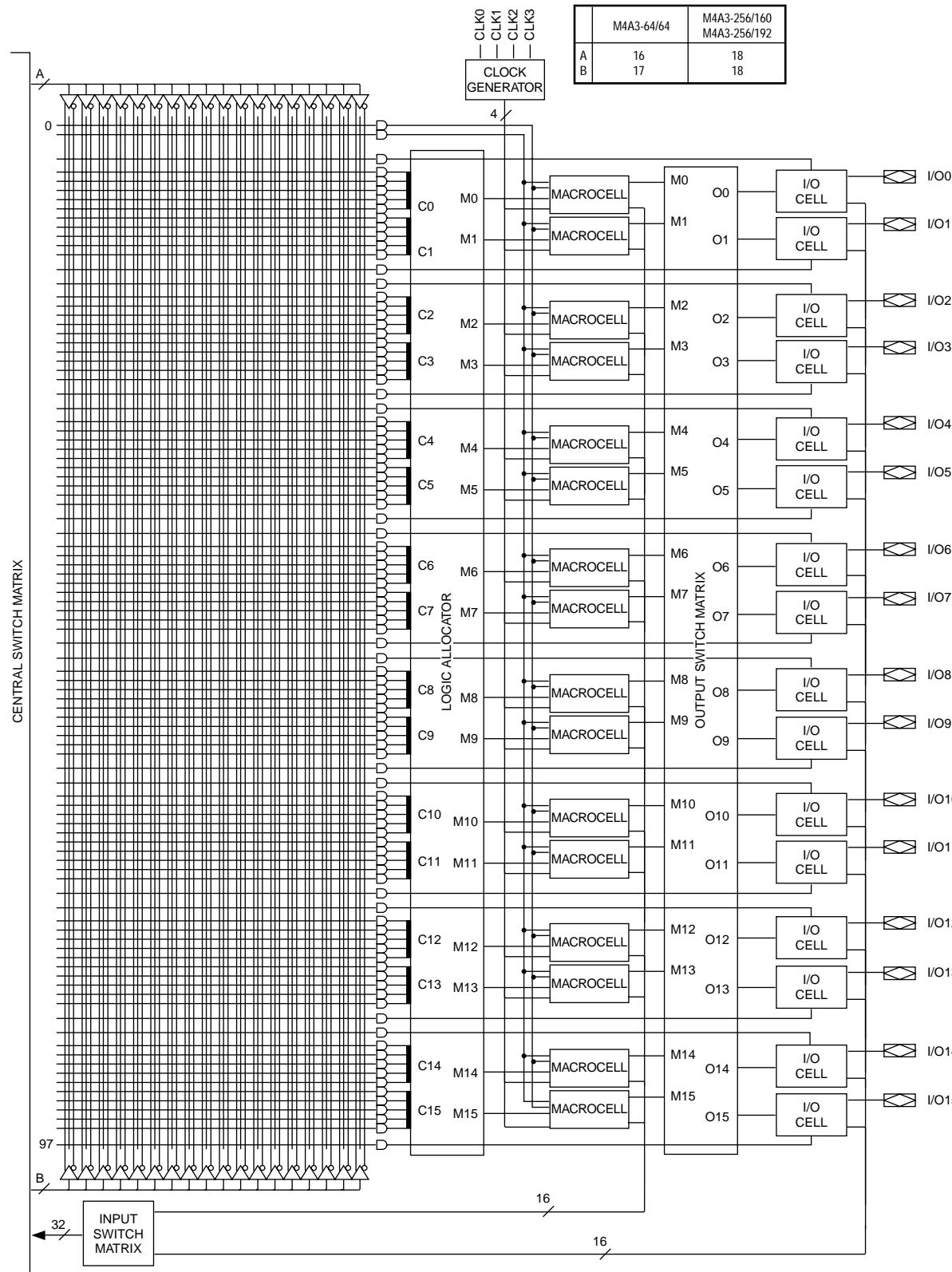
17466G-025

Figure 15. ispMACH 4A Timing Model

SPEEDLOCKING FOR GUARANTEED FIXED TIMING

The ispMACH 4A architecture allows allocation of up to 20 product terms to an individual macrocell with the assistance of an XOR gate without incurring additional timing delays.

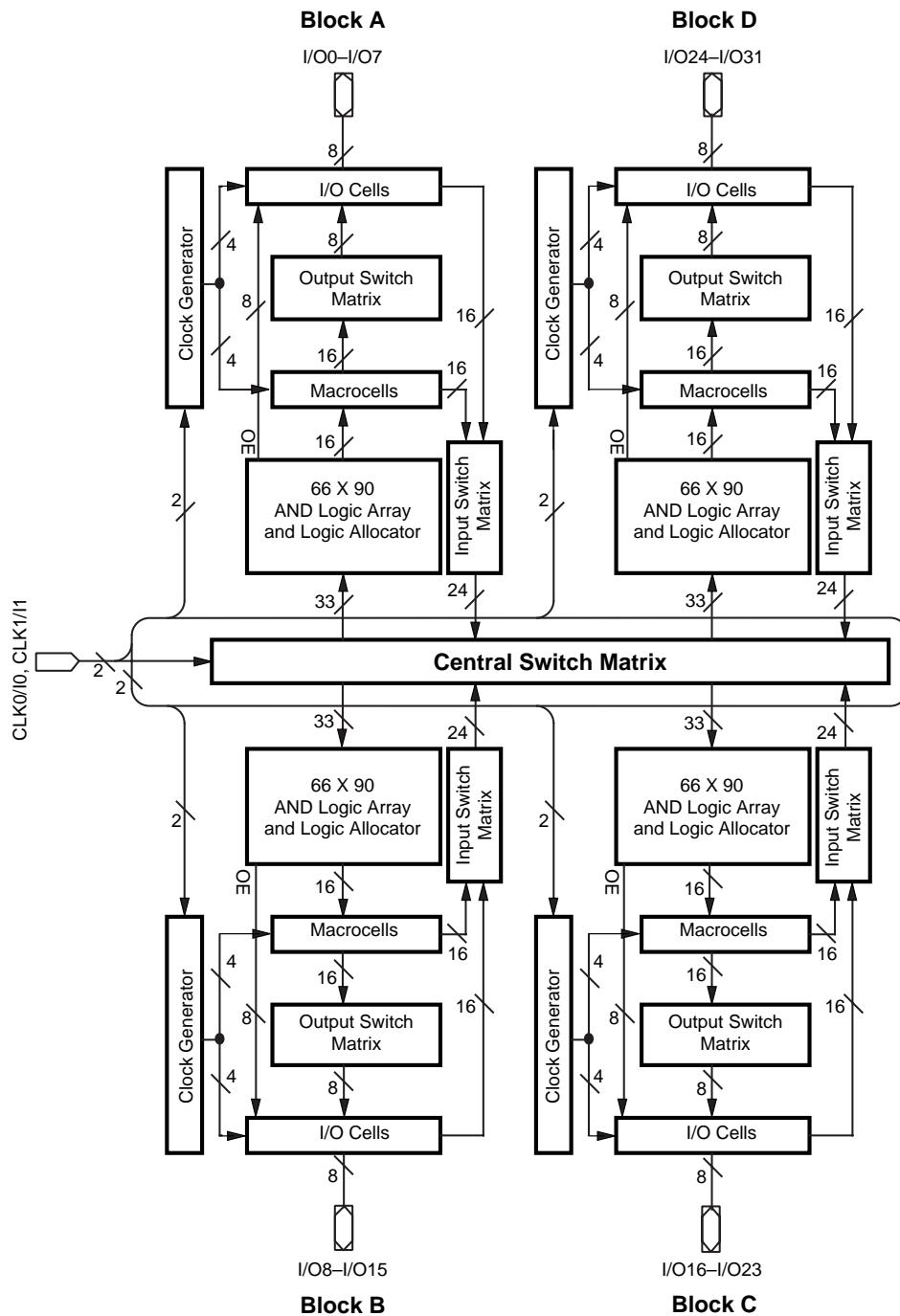
The design of the switch matrix and PAL blocks guarantee a fixed pin-to-pin delay that is independent of the logic required by the design. Other competitive CPLDs incur serious timing delays as product terms expand beyond their typical 4 or 5 product term limits. Speed and SpeedLocking combine to give designs easy access to the performance required in today's designs.



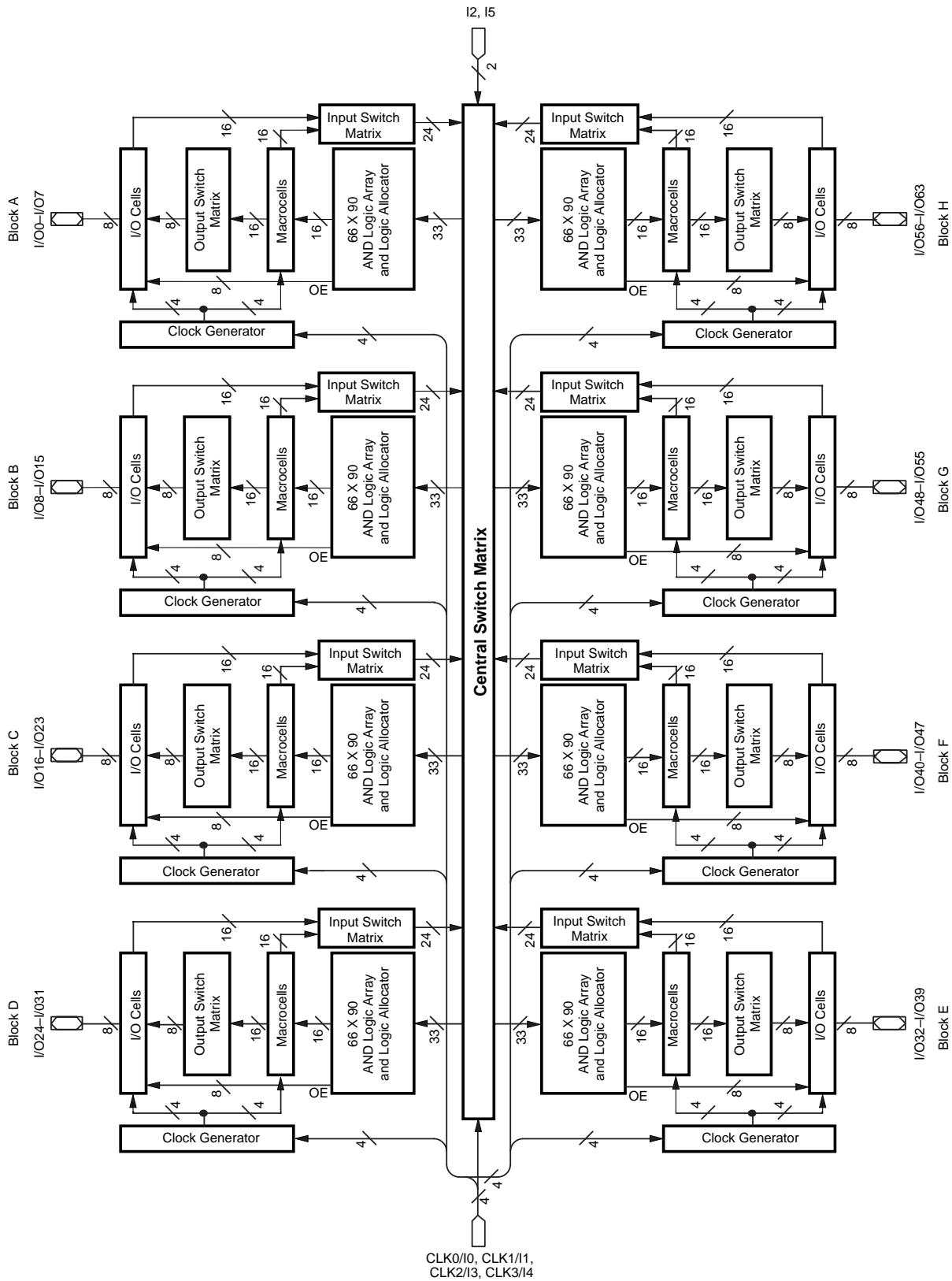
17466H-41

Figure 17. PAL Block for ispMACH 4A Devices with 1:1 Macrocell-I/O Cell Ratio (except M4A (3,5)-32/32)

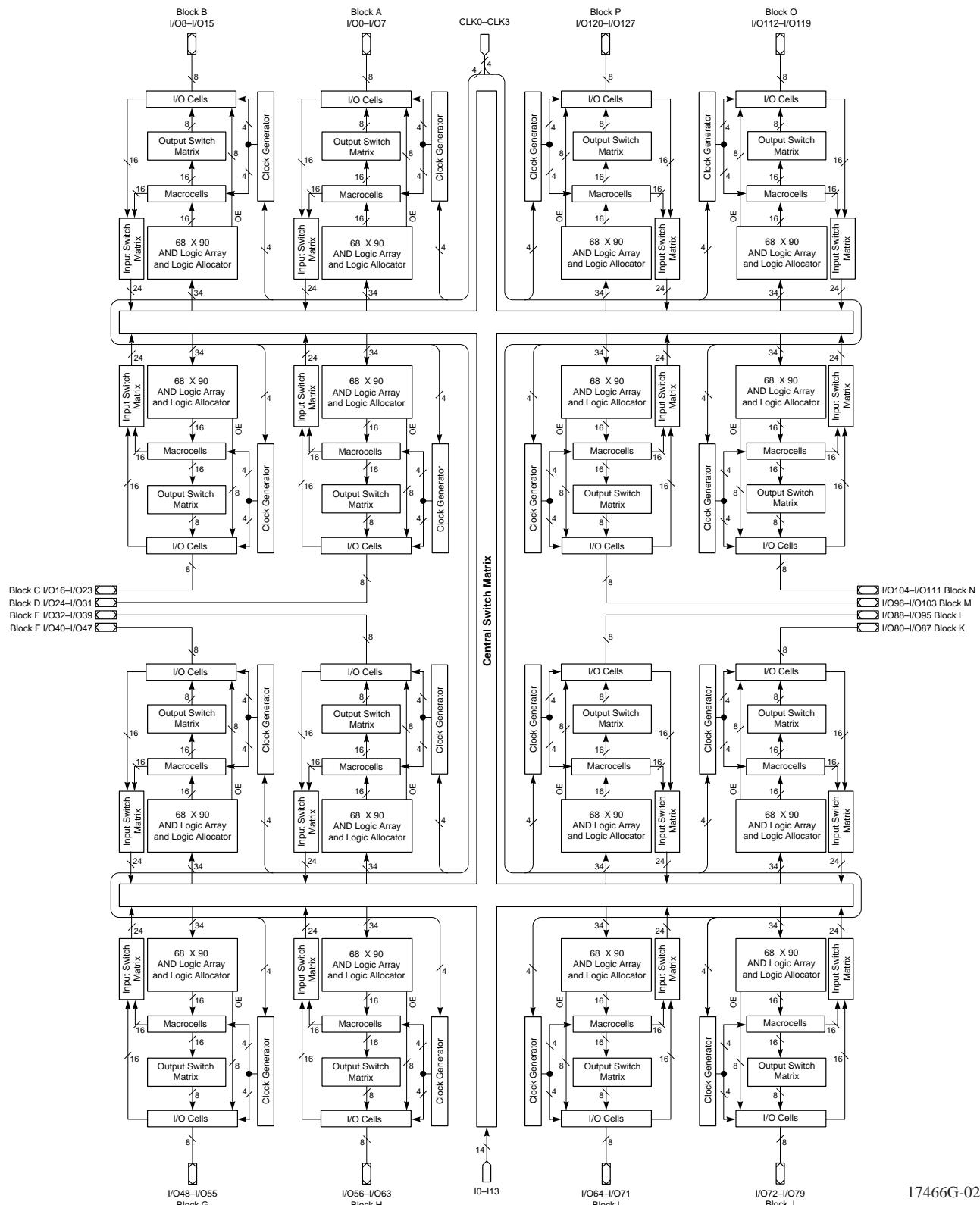
BLOCK DIAGRAM – M4A(3,5)-64/32



BLOCK DIAGRAM – M4A(3,5)-128/64

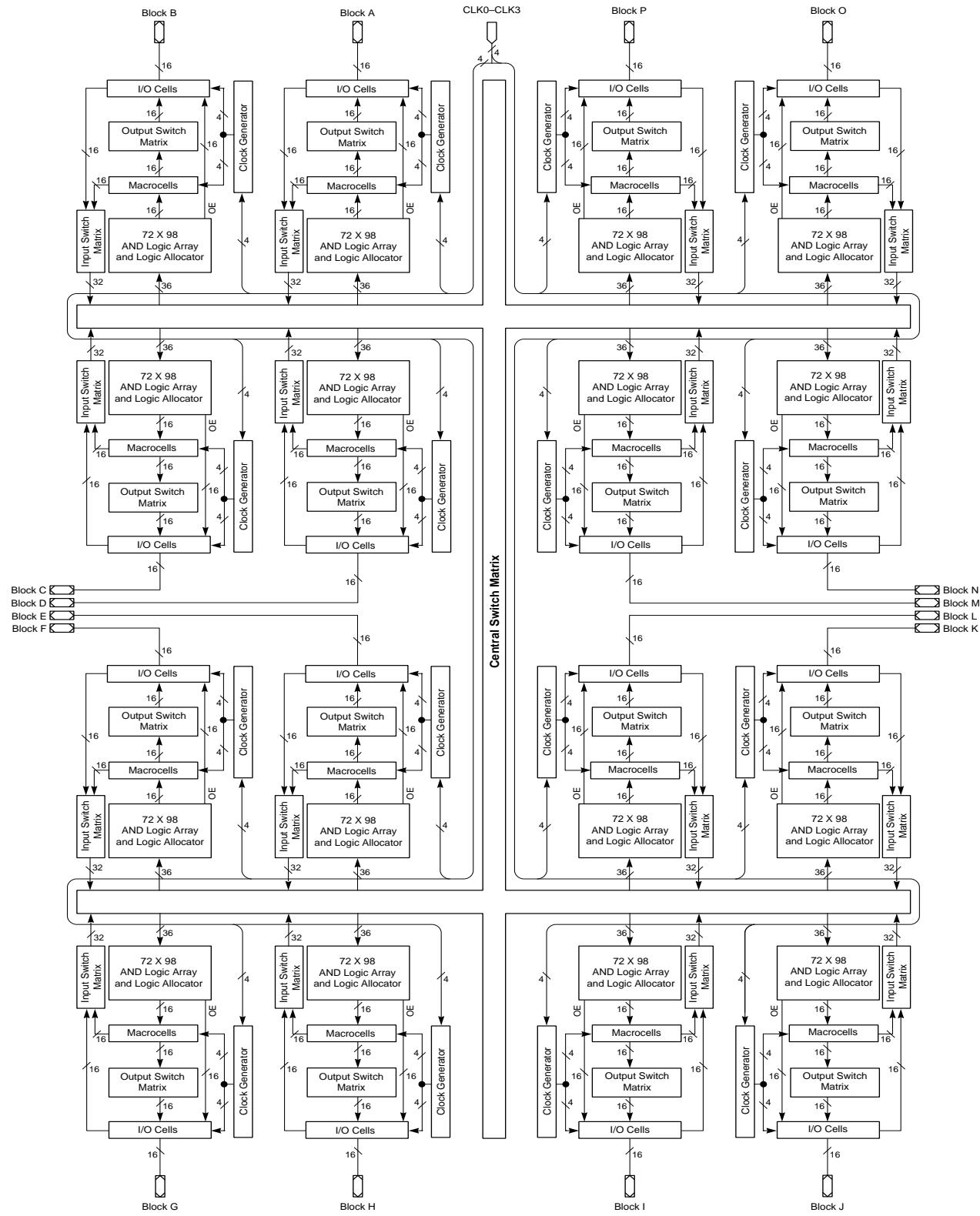


BLOCK DIAGRAM – M4A(3,5)-256/128

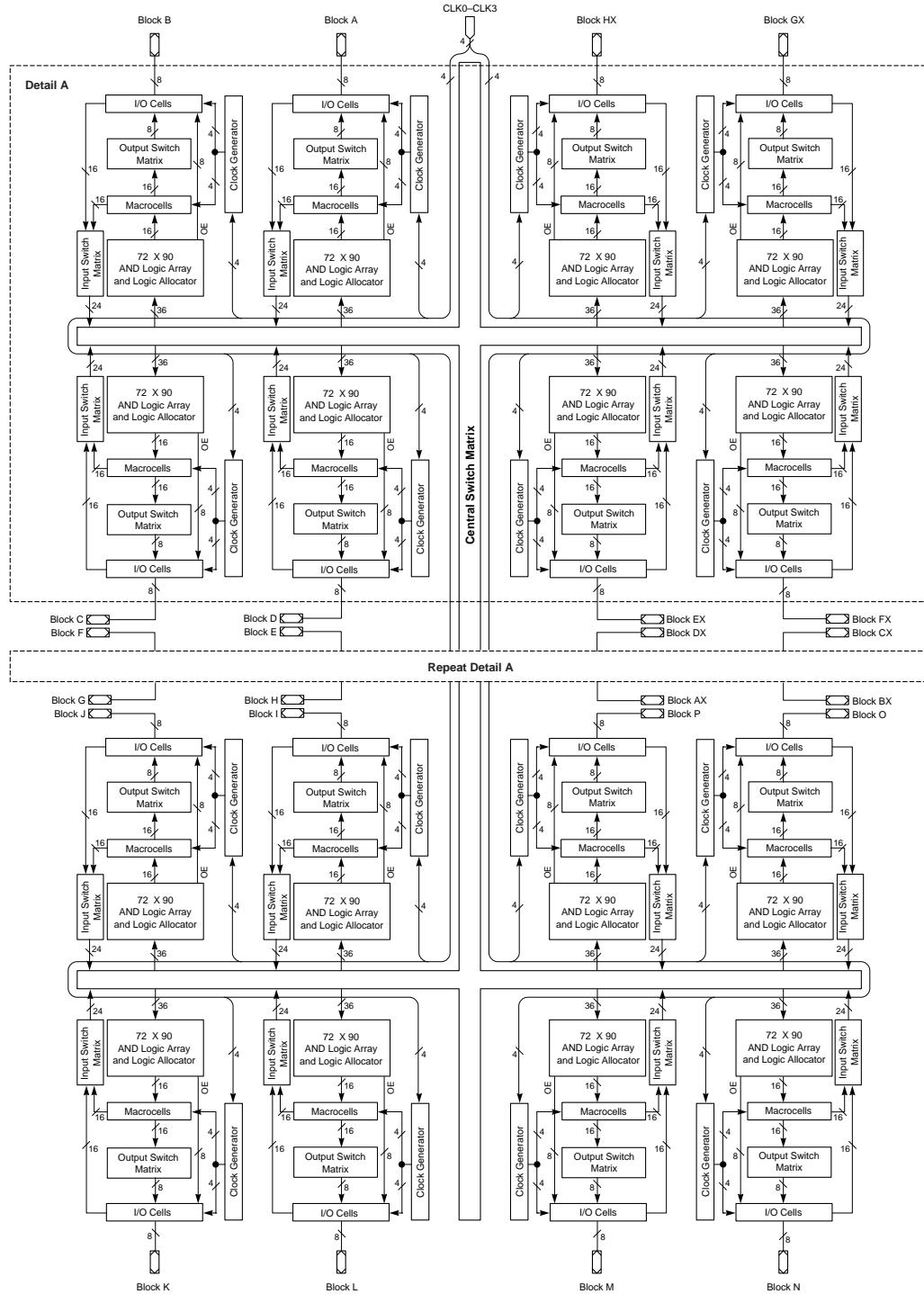


17466G-024

BLOCK DIAGRAM – M4A3-256/160, M4A3-256/192



BLOCK DIAGRAM – M4A3-384/160, M4A3-384/192



ABSOLUTE MAXIMUM RATINGS

M4A3

Storage Temperature	-65°C to +150°C
Ambient Temperature with Power Applied	-55°C to +100°C
Device Junction Temperature	+130°C
Supply Voltage with Respect to Ground	-0.5 V to +4.5 V
DC Input Voltage	-0.5 V to 6.0 V
Static Discharge Voltage	2000 V
Latchup Current ($T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$)	200 mA
<i>Stresses above those listed under Absolute Maximum Ratings may cause permanent device failure. Functionality at or above these limits is not implied. Exposure to Absolute Maximum Ratings for extended periods may affect device reliability.</i>	

OPERATING RANGES

Commercial (C) Devices

Ambient Temperature (T_A)	
Operating in Free Air	0°C to +70°C
Supply Voltage (V_{CC}) with Respect to Ground	+3.0 V to +3.6 V

Industrial (I) Devices

Ambient Temperature (T_A)	
Operating in Free Air	-40°C to +85°C
Supply Voltage (V_{CC}) with Respect to Ground	+3.0 V to +3.6 V
<i>Operating ranges define those limits between which the functionality of the device is guaranteed.</i>	

3.3-V DC CHARACTERISTICS OVER OPERATING RANGES

Parameter Symbol	Parameter Description	Test Conditions	Min	Typ	Max	Unit
V_{OH}	Output HIGH Voltage	$V_{CC} = \text{Min}$	$I_{OH} = -100 \mu\text{A}$	$V_{CC} - 0.2$		V
		$V_{IN} = V_{IH}$ or V_{IL}	$I_{OH} = -3.2 \text{ mA}$	2.4		V
V_{OL}	Output LOW Voltage	$V_{CC} = \text{Min}$	$I_{OL} = 100 \mu\text{A}$		0.2	V
		$V_{IN} = V_{IH}$ or V_{IL} (Note 1)	$I_{OL} = 24 \text{ mA}$		0.5	V
V_{IH}	Input HIGH Voltage	Guaranteed Input Logical HIGH Voltage for all Inputs	2.0		5.5	V
V_{IL}	Input LOW Voltage	Guaranteed Input Logical LOW Voltage for all Inputs	-0.3		0.8	V
I_{IH}	Input HIGH Leakage Current	$V_{IN} = 3.6 \text{ V}$, $V_{CC} = \text{Max}$ (Note 2)			5	μA
I_{IL}	Input LOW Leakage Current	$V_{IN} = 0 \text{ V}$, $V_{CC} = \text{Max}$ (Note 2)			-5	μA
I_{OZH}	Off-State Output Leakage Current HIGH	$V_{OUT} = 3.6 \text{ V}$, $V_{CC} = \text{Max}$ $V_{IN} = V_{IH}$ or V_{IL} (Note 2)			5	μA
I_{OZL}	Off-State Output Leakage Current LOW	$V_{OUT} = 0 \text{ V}$, $V_{CC} = \text{Max}$ $V_{IN} = V_{IH}$ or V_{IL} (Note 2)			-5	μA
I_{SC}	Output Short-Circuit Current	$V_{OUT} = 0.5 \text{ V}$, $V_{CC} = \text{Max}$ (Note 3)	-15		-160	mA

Notes:

1. Total I_{OL} for one PAL block should not exceed 64 mA.
2. I/O pin leakage is the worst case of I_{IL} and I_{OZL} (or I_{IH} and I_{OZH}).
3. Not more than one output should be shorted at a time and duration of the short-circuit should not exceed one second.

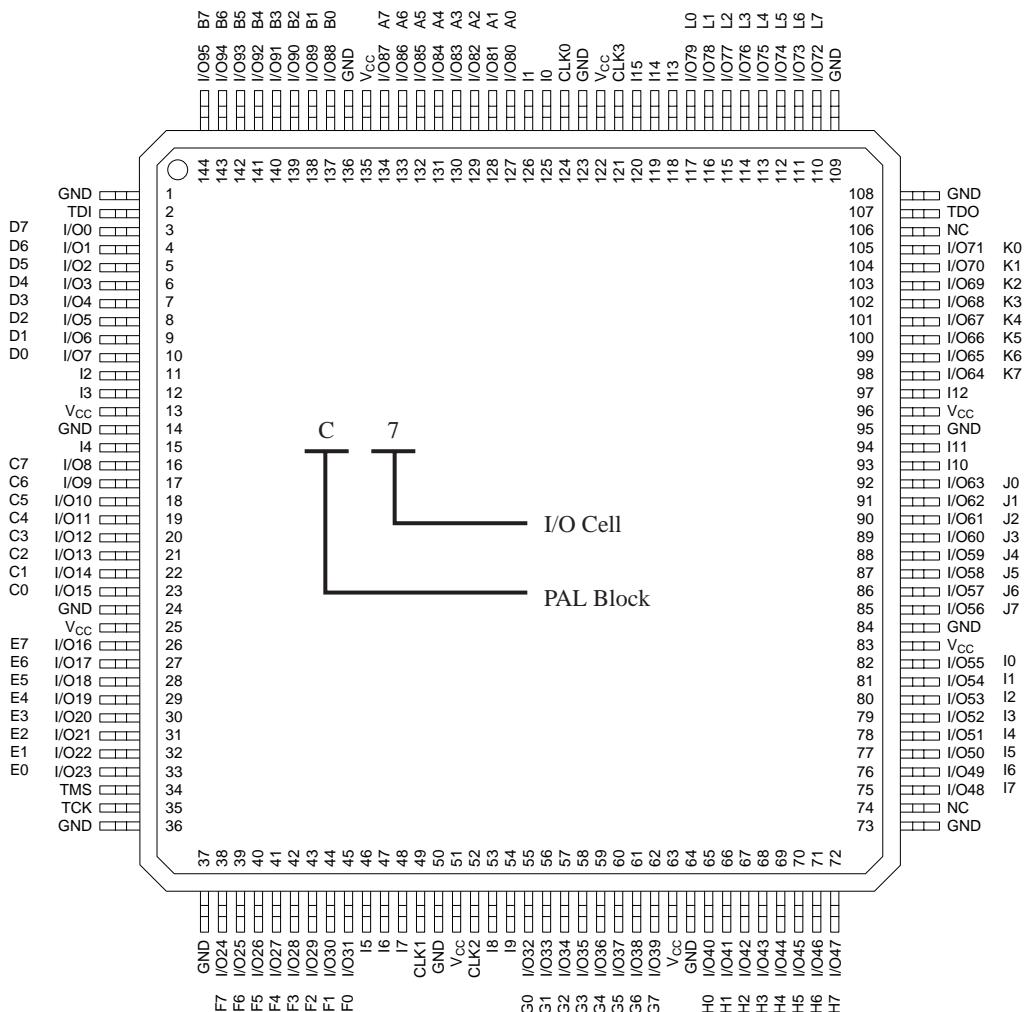
Notes:

1. See "MACH Switching Test Circuit" document on the Literature Download page of the Lattice web site.
2. This parameter does not apply to flip-flops in the emulated mode since the feedback path is required for emulation.

144-PIN TQFP CONNECTION DIAGRAM (M4A(3,5)-192/96)

Top View

144-Pin TQFP



17466G-033

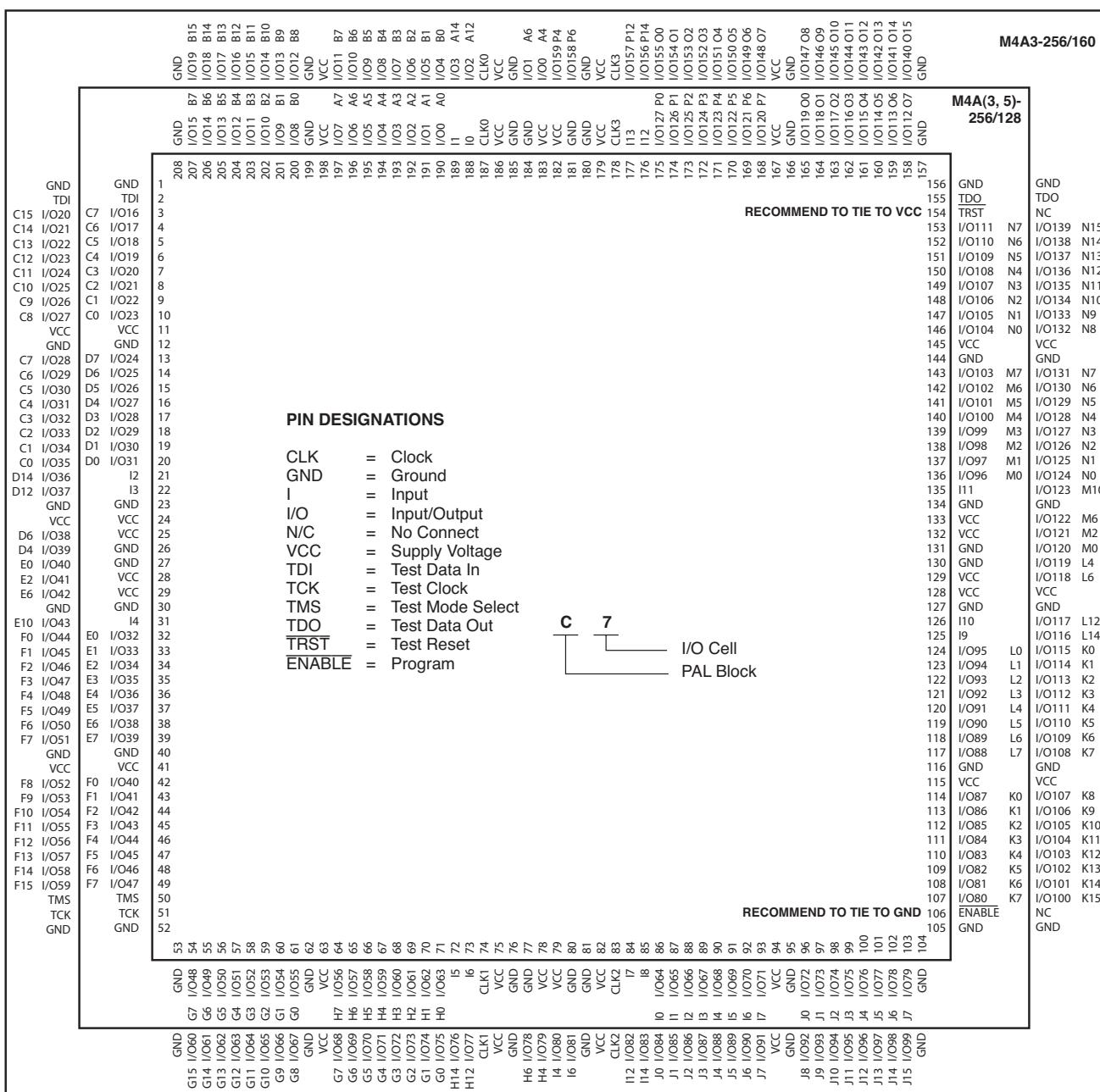
PIN DESIGNATIONS

- CLK = Clock
- GND = Ground
- I = Input
- I/O = Input/Output
- V_{CC} = Supply Voltage
- TDI = Test Data In
- TCK = Test Clock
- TMS = Test Mode Select
- TDO = Test Data Out

208-PIN PQFP CONNECTION DIAGRAM (M4A(3,5)-256/128 AND M4A3-256/160)

Top View

208-Pin PQFP



17466G-044

256-BALL fpBGA CONNECTION DIAGRAM (M4A3-256/128)

Bottom View

256-Ball fpBGA

	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	
A	TRST	I/O117 O5	I/O116 O4	I/O113 O1	I/O126 P6	I/O124 P4	I12	NC	NC	NC	CLK0	I/O1 A1	I/O5 A5	I/O7 A7	I/O10 B2	I/O12 B4 <th>A</th>	A
B	I/O110 N6	I/O111 N7	I/O118 O6	I/O115 O3	I/O127 P7	I/O125 P5	I/O120 P0	NC	NC	NC	I1	I/O2 A2	I/O8 B0	I/O11 B3	I/O13 B5	NC	B
C	I/O108 N4	I/O109 N5	NC	I/O119 O7	I/O114 O2	I/O122 P2	I/O123 P3	NC	NC	I0	I/O4 A4	I/O6 A6	I/O15 B7	I/O14 B6	TDI	I/O23 C7	C
D	NC	I/O104 N0	TDO	GND	GND	VCC	GND	VCC	GND	GND	VCC	GND	VCC	I/O9 B1	I/O22 C6	I/O21 C5	D
E	I/O102 M6	NC	I/O107 N3	VCC	I/O105 N1	I/O106 N2	I13	CLK3	NC	NC	I/O0 A0	NC	GND	I/O20 C4	I/O19 C3	I/O31 D7	E
F	I/O98 M2	I/O103 M7	I/O101 M5	GND	I/O100 M4	I/O99 M3	I/O112 O0	I/O121 P1	NC	NC	I/O3 A3	I/O18 C2	VCC	I/O16 C0	I/O30 D6	I/O29 D5	F
G	NC	I/O96 M0	I11	VCC	NC	I/O97 M1	VCC	GND	VCC	I/O17 C1	I/O28 D4	GND	I/O26 D2	I/O25 D1	I2	G	
H	I/O88 L0	I10	I9	GND	I/O89 L1	I/O90 L2	GND	VCC	VCC	GND	I/O27 D3	I/O24 D0	VCC	NC	NC	NC	H
J	I/O91 L3	I/O92 L4	I/O93 L5	GND	I/O95 L7	I/O94 L6	GND	VCC	VCC	GND	I3	NC	GND	NC	NC	NC	J
K	NC	NC	NC	VCC	NC	NC	VCC	GND	GND	VCC	NC	NC	VCC	I4	NC	I/O32 E0	K
L	NC	NC	I/O80 K0	GND	I/O83 K3	NC	NC	NC	I/O59 H3	I/O61 H5	NC	NC	GND	I/O35 E3	I/O36 E4	I/O33 E1	L
M	I/O81 K1	I/O82 K2	I/O84 K4	GND	I/O67 I3	I/O65 I1	NC	NC	I/O58 H2	I/O48 G0	I/O51 G3	NC	VCC	I/O44 F4	I/O39 E7	I/O34 E2	M
N	I/O85 K5	I/O86 K6	ENABLE	VCC	GND	VCC	GND	VCC	GND	GND	VCC	GND	GND	TCK	I/O40 F0	I/O37 E5	N
P	I/O87 K7	I/O77 J5	I/O78 J6	I/O79 J7	I/O68 I4	I/O66 I2	NC	NC	NC	I6	I/O63 H7	I/O52 G4	I/O55 G7	TMS	I/O41 F1	I/O38 E6	P
R	I/O76 J4	I/O75 J3	I/O72 J0	I/O71 I7	I/O64 I0	I7	NC	NC	NC	I/O56 H0	I/O60 H4	I/O49 G1	I/O53 G5	I/O47 F7	I/O43 F3	I/O42 F2	R
T	I/O74 J2	I/O73 J1	I/O70 I6	I/O69 I5	I8	CLK2	NC	NC	CLK1	I5	I/O57 H1	I/O62 H6	I/O50 G2	I/O54 G6	I/O46 F6	I/O45 F5	T
	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	

PIN DESIGNATIONS

CLK = Clock
 GND = Ground
 I = Input
 I/O = Input/Output
 N/C = No Connect
 VCC = Supply Voltage
 TDI = Test Data In
 TCK = Test Clock
 TMS = Test Mode Select
 TDO = Test Data Out
 TRST = Test Reset
 ENABLE = Program



m4a3.256.128_256bga

ispMACH 4A PRODUCT ORDERING INFORMATION

ispMACH 4A Devices Commercial and Industrial - 3.3V and 5V

Lattice programmable logic products are available with several ordering options. The order number (Valid Combination) is formed by a combination of:

M4A3-	256 / 128	-7	Y	C	T ₄₈	= 48-pin TQFP for M4A3-32/32 or M4A3-64/32 M4A5-32/32 or M4A5-64/32
FAMILY TYPE						OPERATING CONDITIONS
M4A3- = ispMACH 4A Family Low Voltage Advanced Feature (3.3-V V _{CC})						C = Commercial (0°C to +70°C)
M4A5- = ispMACH 4A Family Advanced Feature (5-V V _{CC})						I = Industrial (-40°C to +85°C)
MACROCELL DENSITY						PACKAGE TYPE
32 = 32 Macrocells	192 = 192 Macrocells					SA = Ball Grid Array (BGA)
64 = 64 Macrocells	256 = 256 Macrocells					J = Plastic Leaded Chip Carrier (PLCC)
96 = 96 Macrocells	384 = 384 Macrocells					JN = Lead-free Plastic Leaded Chip Carrier (PLCC)
128 = 128 Macrocells	512 = 512 Macrocells					V = Thin Quad Flat Pack (TQFP)
I/Os						VN = Lead-free Thin Quad Flat Pack (TQFP)
/32 = 32 I/Os in 44-pin PLCC, 44-pin TQFP or 48-pin TQFP						Y = Plastic Quad Flat Pack (PQFP)
/48 = 48 I/Os in 100-pin TQFP						YN = Lead-free Plastic Quad Flat Pack (PQFP)
/64 = 64 I/Os in 100-pin TQFP, 100-pin PQFP, or 100-ball caBGA						FA = Fine-pitch Ball Grid Array (fpBGA)
/96 = 96 I/Os in 144-pin TQFP or 144-ball fpBGA						FAN = Lead-free Fine-pitch Ball Grid Array (fpBGA)
/128 = 128 I/Os in 208-pin PQFP, 256-ball BGA or 256-ball fpBGA						CA = Chip-array Ball Grid Array (caBGA)
/160 = 160 I/Os in 208-pin PQFP						
/192 = 192 I/Os in 256-ball BGA or 256-ball fpBGA						
/256 = 256 I/Os in 388-ball fpBGA						
SPEED						
						-5 = 5.0 ns t _{PD}
						-55 = 5.5 ns t _{PD}
						-6 = 6.0 ns t _{PD}
						-65 = 6.5 ns t _{PD}
						-7 = 7.5 ns t _{PD}
						-10 = 10 ns t _{PD}
						-12 = 12 ns t _{PD}
						-14 = 14 ns t _{PD}

*Package obsolete, contact factory.

Conventional Packaging

3.3V Commercial Combinations		
M4A3-32/32	-5, -7, -10	JC, VC, VC48
M4A3-64/32		JC, VC, VC48
M4A3-64/64		VC
M4A3-96/48		VC
M4A3-128/64		YC, VC, CAC
M4A3-192/96	-6, -7, -10	VC, FAC
M4A3-256/128	-55, -65 ¹ , -7, -10	YC, FAC, SAC
M4A3-256/160		YC
M4A3-256/192	-7, -10	FAC
M4A3-384/160		YC
M4A3-384/192	-65, -10, -12	SAC, FAC
M4A3-512/160		YC
M4A3-512/192	-7, -10, -12	FAC
M4A3-512/256		FAC

3.3V Industrial Combinations		
M4A3-32/32		JI, VI, VI48
M4A3-64/32		JI, VI, VI48
M4A3-64/64		VI
M4A3-96/48		VI
M4A3-128/64		YI, VI, CAI
M4A3-192/96		VI, FAI
M4A3-256/128		YI, FAI, SAI
M4A3-256/160		YI
M4A3-256/192	-10, -12	FAI
M4A3-384/160		YI
M4A3-384/192		FAI
M4A3-512/160		YI
M4A3-512/192	-10, -12, -14	FAI
M4A3-512/256		FAI

1. Use 5.5ns for new designs.

Revision History

Date	Version	Change Summary
-	K	Previous Lattice release.
August 2006	L	Updated for lead-free package options.
September 2006	M	Revised M4A3-256/160 208-pin PQFP connection diagram.